

[METHOD OF BOOSTING WAFER CLEANING EFFICIENCY AND INCREASING PROCESS YIELD]

Abstract of Disclosure

A method of boosting wafer-cleaning efficiency and increasing process yield. Different types of process particles are deposited on a test wafer. The test wafer is cleaned in a cleaning operation. The test wafer is scanned to determine the types of process particles that are completely removed and the types of process particles that remain over the test wafer. The results of wafer scanning are used to provide an assessment of the efficiency of the cleaning operation. Operation parameters of the cleaning operation are adjusted to maximize the wafer-cleaning efficiency.

Figures